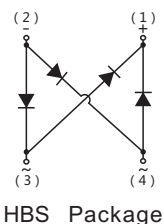


Features

- Surface mount bridge, small package;
- Ideal for printed circuit boards;
- Glass passivated chip junction;
- High forward current capability up to 8.0A;
- High surge current capability;
- High heat dissipation capability;
- Low profile package;
- Low forward voltage drop;
- Plastic package has Underwrites Laboratory Flammability Classification 94V-0;

Mechanical Data

- Case: HBS;
- Epoxy meets UL-94V-0 Flammability rating;
- Terminals: Matte tin plated leads, solderable per J-STD-002 and JESD22-B102;
- High temperature soldering guaranteed:
Solder Reflow 260 °C, 10 seconds;
- Polarity: As marked on body;
- Marking: Type number;



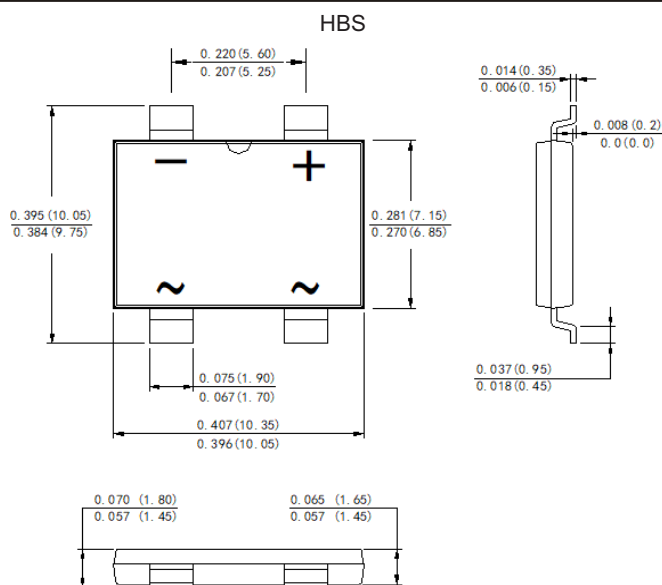
HBS Package

VOLTAGE RANGE

200 to 1000 Volts

CURRENT

8.0 Amperes



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	RHBS802	RHBS804	RHBS806	RHBS808	RHBS810	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	200	400	600	800	1000	V
Average Rectified Output Current	I _O	8.0					A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	200					A
I ² t Rating for Fusing	I ² t	166					A ² S
Maximum Forward Voltage at 1.0 A	V _F	0.83 (max.)					V
Maximum Forward Voltage at 8.0 A	V _F	1.3					V
Maximum DC Reverse Current @ T _A =25 °C at Rated DC Blocking Voltage @ T _A =125 °C	I _R	0.20 100					μA
Maxumum reverse recovery time (IF=0.5A,IR=1.0A,Irr=0.25A)	Trr	150		250	500		nS
Typical Junction Capacitance (Note1)	C _j	48					pF
Typical Thermal Resistance (Note2)	R _{BJA} R _{BJC} R _{BJL}	70.0 15.0 22.0					°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150					°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

RATING AND CHARACTERISTIC CURVES (RHBS802 THRU RHBS810)

FIG.1 Derating Curve Output Rectified Current

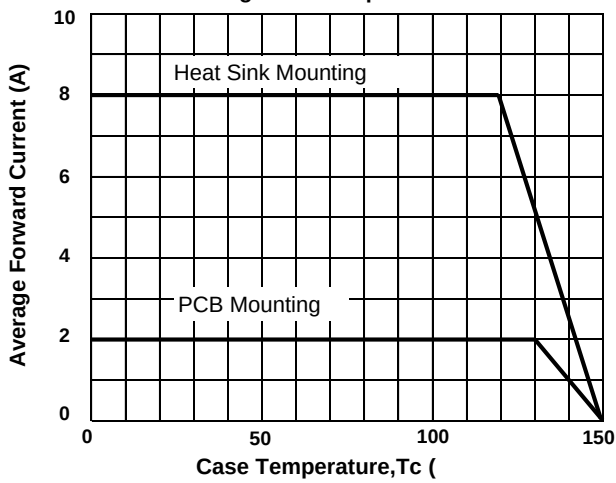


FIG.2 Typical Forward Characteristics per Diode

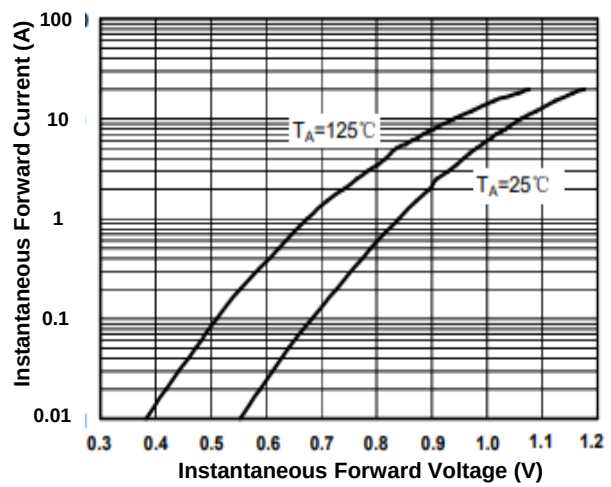


FIG.3 Maximum Non-Repetitive Peak Forward Surge Current per Diode

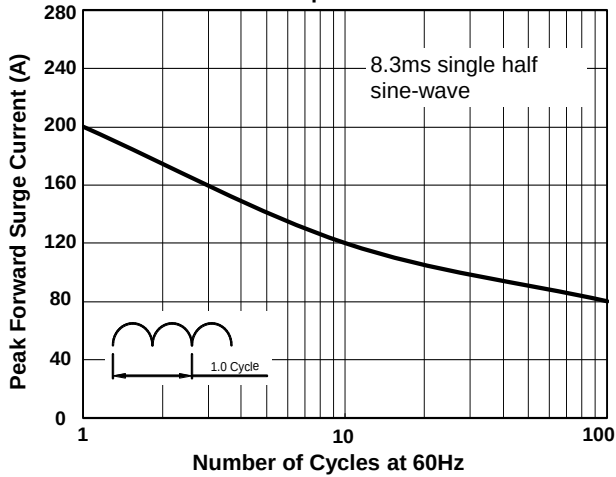


FIG.4 Typical Reverse Characteristics per Diode

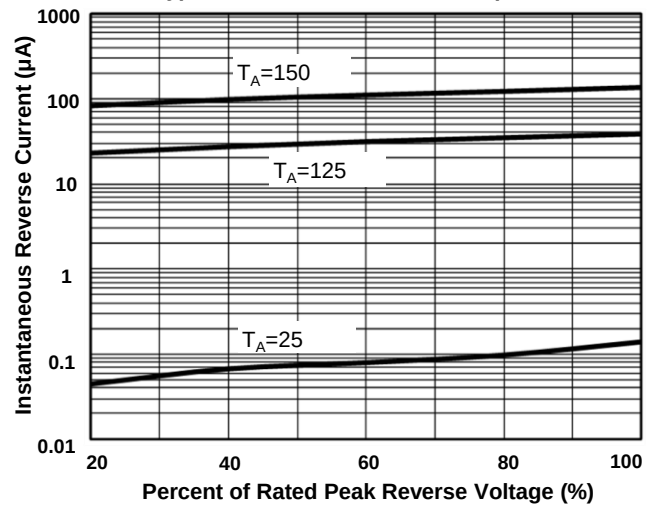
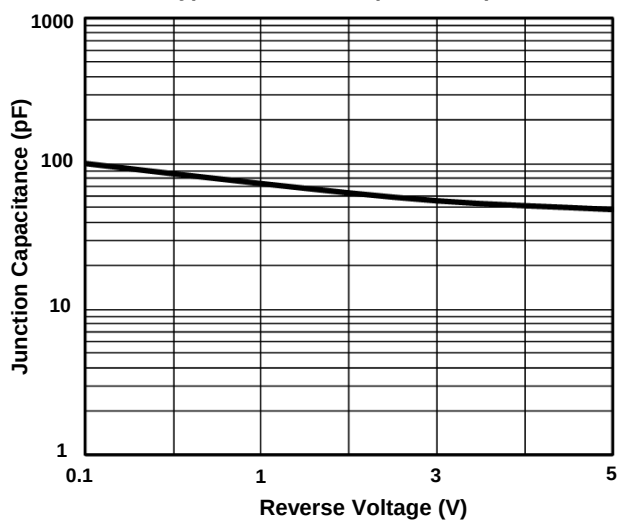


FIG.5 Typical Junction Capacitance per Diode



Suggested PCB printfoot layout

